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2013年12月

FDD1600N10ALZ

N 沟道 PowerTrench[®] MOSFET 100 V, 6.8 A, 160 m Ω

特性

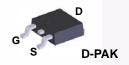
- $R_{DS(on)} = 124 \text{ m}\Omega \text{ (Typ.)}@V_{GS} = 10 \text{ V, } I_D = 3.4 \text{ A}$
- $R_{DS(on)} = 175 \text{ m}\Omega \text{ (Typ.)}@V_{GS} = 5 \text{ V}, I_D = 2.1 \text{ A}$
- 低栅极电荷 (典型值 2.78 nC)
- 低 C_{rss} (典型值 2.04 pF)
- 快速开关
- 100% 经过雪崩测试
- 改善的 dv/dt 处理能力
- 符合 RoHS 标准

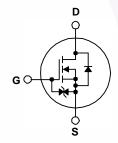
说明

该 N 沟道 MOSFET 采用飞兆半导体的先进 Power Trench® 工艺 生产,这一先进工艺专用于最小化通态电阻,同时保持卓越的开关性能。

应用

- 消费电子设备
- LED 电视和显示器
- 同步整流
- 不间断电源
- 微型太阳能逆变器





MOSFET 最大额定值 T_C=25℃ 除非另有说明。

符号		FDD1600N10ALZ	单位	
V _{DSS}	漏极一源极电压		100	V
V_{GSS}	栅极一源极电压		±20	V
	运机 中 法	-连续 (T _C = 25°C)	6.8	A
ID	漏极电流	-连续 (T _C = 100°C)	4.3	A
I _{DM}	漏极电流	漏极电流 —脉冲 (注 1)		
E _{AS}	单脉冲雪崩能量	单脉冲雪崩能量 (注 2)		
dv/dt	二极管恢复 dv/dt 峰值	(注 3)	6.0	V/ns
Б	-1. +1	$(T_C = 25^{\circ}C)$	14.9	W
P_{D}	功耗	-超过 25°C 时降额	0.12	W/°C
T _J , T _{STG}	工作和存储温度范围	-55 至 +150	°C	
TL	用于焊接的最大引脚温度, 距离	外壳 1/8", 持续 5 秒	300	°C

热性能

符号	参数	FDD1600N10ALZ	单位
$R_{\theta JC}$	结至外壳热阻最大值	8.4	°C/W
$R_{\theta JA}$	结至环境热阻最大值	87	*C/VV

封装标识与定购信息

器件编号	顶标	封装	包装方法	卷尺寸	带宽	数量
FDD1600N10ALZ	1600N10ALZ	DPAK	卷带	330 mm	16 mm	2500 单元

测试条件

最小值 典型值

最大值

单位

电气特性 T_C=25℃ 除非另有说明。

关断特性						
BV _{DSS}	漏极一源极击穿电压	$I_D = 250 \mu A, V_{GS} = 0 V$	100	-	-	V
ΔBV _{DSS} / ΔT _J	击穿电压温度系数	I _D = 250 μA,参考 25°C	-	0.1	-	V/°C
1	零栅极电压漏极电流	$V_{DS} = 80 \text{ V}, V_{GS} = 0 \text{ V}$	-	-	1	μА
DSS	令'''' '' '\ '\ '\ '\ '\ '\ '\ '\ '\ '\ '\	$V_{DS} = 80 \text{ V}, V_{GS} = 0 \text{ V}, T_{C} = 125^{\circ}\text{C}$	-	-	500	μΛ
I_{GSS}	栅极-源极漏电流	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$	-	-	±10	μΑ

导通特性

符号

V _{GS(th)}	栅极阈值电压	$V_{GS} = V_{DS}, I_{D} = 250 \mu\text{A}$	1.4	-	2.8	V
Page	中国不压团种土口及上加	$V_{GS} = 10 \text{ V}, I_D = 3.4 \text{ A}$	-	124	160	mΩ
R _{DS(on)} 漏极至源极静态导通电阻	$V_{GS} = 5 \text{ V}, I_D = 2.1 \text{ A}$	-	175	375	1115.2	
9FS	正向跨导	$V_{DS} = 10 \text{ V}, I_D = 6.8 \text{ A}$	-	19.6	-	S

动态特性

C _{iss}	输入电容	., 50.1/.1/	0.1/	-	169	225	pF
C _{oss}	输出电容	V _{DS} = 50 V, V _{GS} = f = 1 MHz	= U V,	-	43	55	pF
C _{rss}	反向传输电容	-1 - 1 IVII IZ		- \	2.04	-	pF
C _{oss(er)}	能源相关输出电容	$V_{DS} = 50 \text{ V}, V_{GS} =$	0 V	\	85	-	pF
$Q_{g(tot)}$	10V 的栅极电荷总量	$V_{GS} = 10 \text{ V}$	V _{DD} = 50 V,	-	2.78	3.61	nC
$Q_{g(tot)}$	5V 的栅极电荷总量	$V_{GS} = 5 V$	I _D = 6.8 A		1.5	1.95	nC
Q_{gs}	栅极-源极栅极电荷				0.72	•	nC
Q_{gd}	栅极一漏极"密勒"电荷				0.56	•	nC
V _{plateau}	栅极电场电压		(说明 4)	-	4.02	•	V
Q _{sync}	总栅极电荷同步	$V_{DS} = 0 \text{ V}, I_{D} = 3.4$	4 A	-	2.5	•	nC
Q _{oss}	输出电荷	$V_{DS} = 50 \text{ V}, V_{GS} =$	= 0 V	- /	5.2	-	nC
ESR	等效串联电阻 (G-S)	f = 1 MHz		-	2.1	-	Ω

开关特性

t _{d(on)}	导通延迟时间		-	7	24	ns
t _r	开通上升时间	$V_{DD} = 50 \text{ V}, I_{D} = 6.8 \text{ A},$	-	2	14	ns
t _{d(off)}	关断延迟时间	V_{GS} = 10 V, R_G = 4.7 Ω	-	13	36	ns
t _f	关断下降时间	(说明	1) -	2	14	ns

漏极-源极二极管特性

Is	漏极一源极二极管最大正向连续电流		-	-	6.8	Α
I _{SM}	漏极一源极二极管最大正向脉冲电流		-	-	13.6	Α
V_{SD}	漏极 一源极二极管正向电压	V _{GS} = 0 V, I _{SD} = 6.8 A	-	-	1.3	V
t _{rr}	反向恢复时间	$V_{GS} = 0 \text{ V}, I_{SD} = 6.8 \text{ A}, V_{DS} = 50 \text{ V},$	-	37	-	ns
Q_{rr}	反向恢复电荷	$dI_F/dt = 100 A/\mu s$	ı	42	-	nC

- 1. 重复额定值: 脉冲宽度受限于最大结温。 2. L = 1 mH, I_{AS} = 3.18 A, R_{G} = 25 Ω , 启动 T_{J} = 25°C。 3. I_{SD} ≤ 6.8 A, di/dt ≤ 200 A/μs, V_{DD} ≤ BV_{DSS}, 启动 T_{J} = 25°C。
- 4. 本质上独立于工作温度的典型特性。

典型性能特征

图 1. 导通区域特性

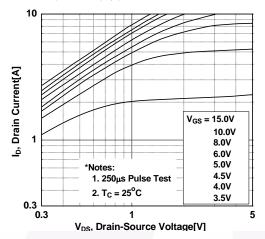


图3. 导通电阻变化与漏极电流和栅极电压

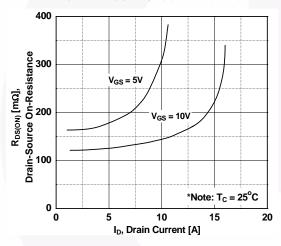


图 5. 电容特性

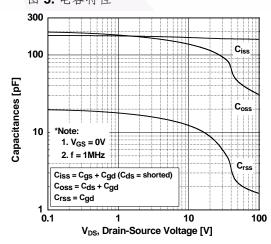


图 2. 传输特性

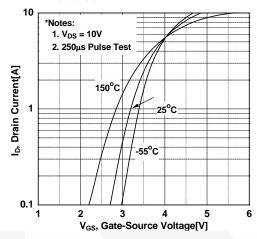


图 4. 体二极管正向电压变化与源电流和温度

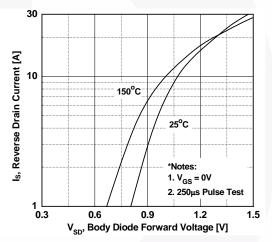
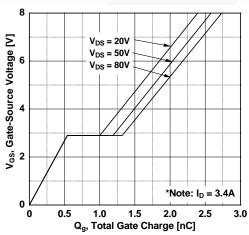
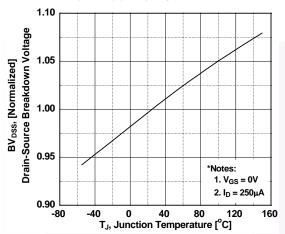


图 6. 栅极电荷



典型性能特征 (接上页)

图 7. 击穿电压变化与温度



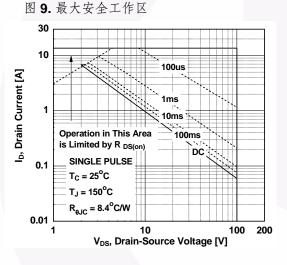


图 11. Eoss 与漏极至源极电压

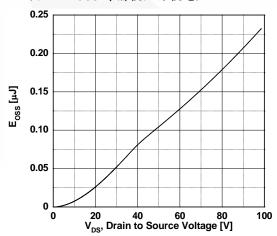


图 8. 导通电阻变化与温度

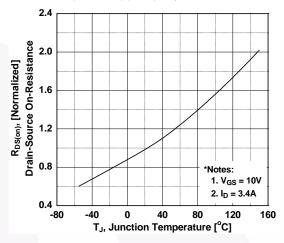


图 10. 最大漏极电流与壳体温度

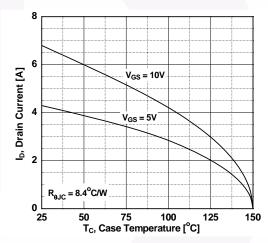
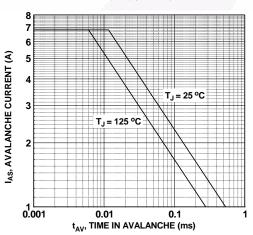
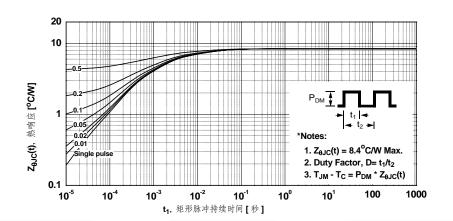


图 12. 非箝位感性开关能力



典型性能特征 (接上页)

图 13. 瞬态热响应曲线



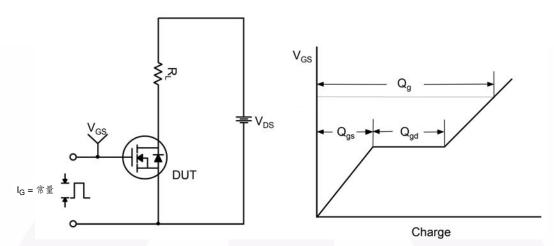


图 14. 栅极电荷测试电路与波形

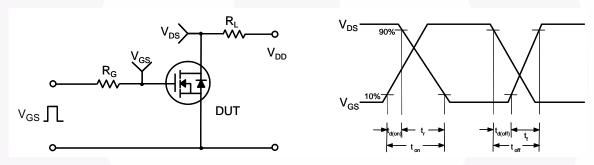


图 15. 阻性开关测试电路与波形

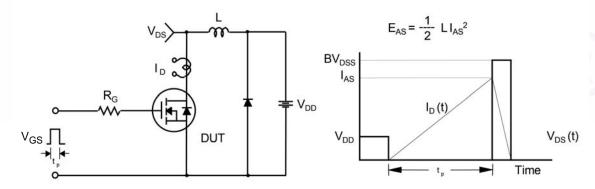
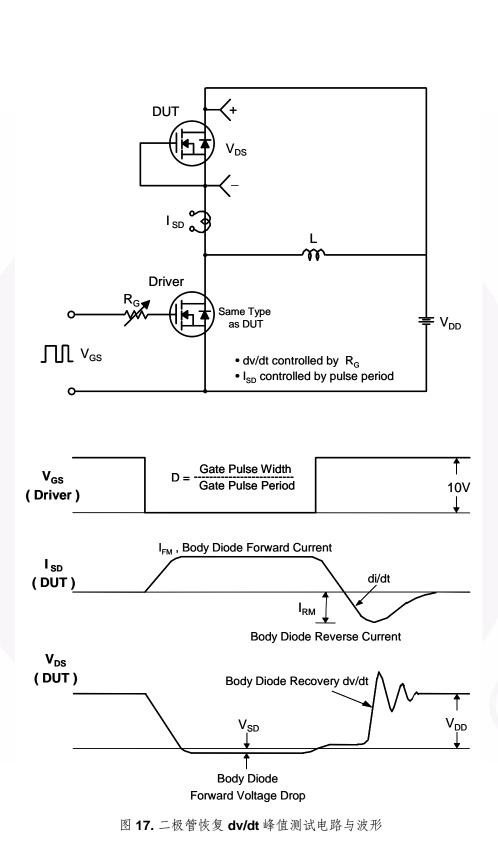


图 16. 非箝位感性开关测试电路与波形



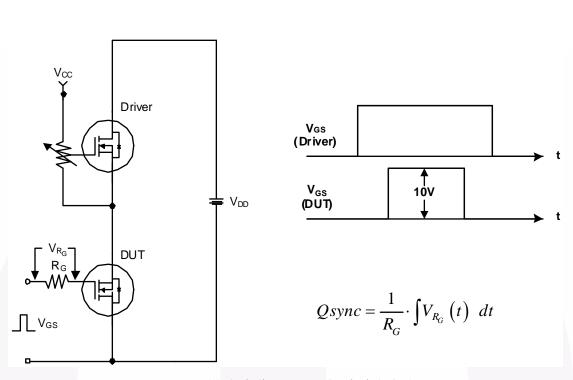


图 18. 总栅极电荷 Qsync. 测试电路和波形

机械尺寸

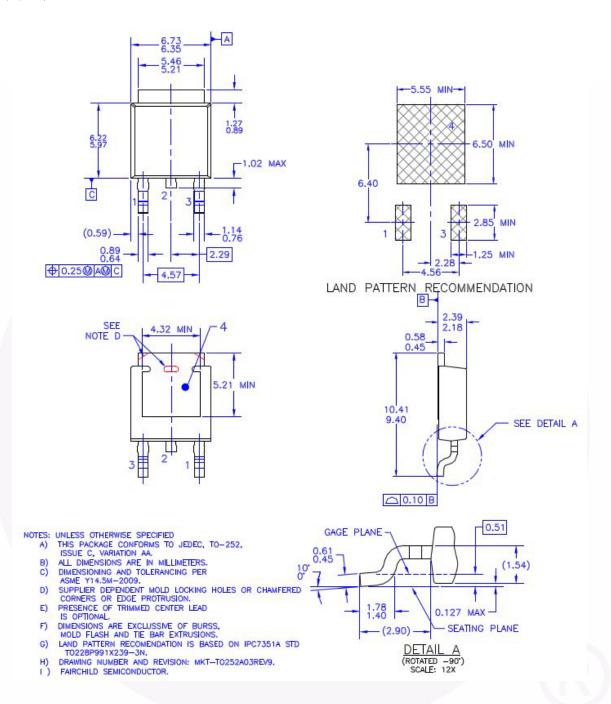


图 19. TO252 (D-PAK),模塑, 3 引脚,选项 AA&AB

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